

File E102269
05NK26022

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REPORT

on

COMPONENT - AUXILIARY DEVICES

Watlow Winona Inc.
Winona, MN

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PRODUCT COVERED:

*USR, CNR Heat Sink Assembly, STRT-HS, followed by AA or CB-, followed by any three numbers or letters, followed by **B, C, D, E or F.**

Base Module Assembly, STRT-BASE-, followed by 0000 or DP, followed by A, B or F, followed by 1, 2 or 3.

Control Module Assembly, STRC-, followed by any number or letter, followed by K, B, P, E, H, D, J or C, followed by A, B or L, followed by L, H, 1, 2 or 3, followed by any four numbers or letters

GENERAL:

These devices are open type, single phase, temperature control devices with integrated solid state relay output for resistive load control. Options exist for redundant monitor device with mechanical contactor shutdown of load power. A system consists of a control module and base module along with some type of heatsink. If the heatsink module p/n above is part of system, see Listed File E102236, Vol. 2, Sec. 4 for system part number details.

RATINGS:

Electrical - Units are rated as follows:

* Load Power (Base and Heat sink module) - 240 Vac to 600 V ac, 25 **A**, 40 A **or 75 A** model dependant.

Control Power - 24 to 28 Vac/dc or 100-240 V ac/dc, 50/60 Hz, 12 VA control module only, 50 VA with on board contactor or 140 VA with external contactor

Temperature - Maximum 70 °C. Current ratings are based on a 50 °C ambient and derated above based on figure 1.

NOMENCLATURE:

Heat Sink Module

<u>STRT-HS</u>	<u>AA-</u>	<u>000</u>	<u>B</u>
I	II	III	IV

- I. Heat sink assembly model family
STRT-HS
- II. Base Module Options
AA = Control Only Base
CB = Contactor Base
- III. Custom Options
000 = Standard Product
Any three numbers or letters = Cosmetic options
- IV. Heat Sink Amperage
B = 25 A
C = 40 A
D = 75 A, 24 V dc fan cooled heatsink*
E = 75 A, 120 V ac fan cooled heatsink*
F = 75 A, 240 V ac fan cooled heatsink*

***Item II must be AA with these models.**

Base Module

<u>STRT-BASE-</u>	<u>DP-</u>	<u>F</u>	<u>1</u>
I	II	III	IV

- I. Base Module Assembly Family
STRT-BASE-
- II. Base Module Type
00 = Control Only Base
DP = Contactor Base
- III. Mechanical Contactor Type
0 or A = No contactor
B = 40 A single pole
F = 40 A dual pole
- IV. Contactor Voltage
0 = No Contactor
1 = 24 Vac
2 = 120 Vac
3 = 208/240 Vac

Control Module

<u>STRC-</u>	<u>0</u>	<u>K</u>	<u>L</u>	<u>1</u>	<u>-AAAA</u>
I	II	III	IV	V	VI

- I. Control Module Assembly Family
STRC-
- II. Future Expansion Placeholder
0 = Current Model
Any number or letter = Future Non-Critical Options
- III. Control Output #2 and I/O Options
*K = 0.5A SSR
*B = 0.5A SSR, Two Digital I/O
*P = 0.5A SSR, Current Measurement
*E = 0.5A SSR, Two Digital I/O, Current Measurement
*H = 5A Relay
*D = 5A Relay, Two Digital I/O
*J = 5A Relay, Current Measurement
*C = 5A Relay, Two Digital I/O, Current Measurement
- IV. Limit Card Options
A = No Limit card
L = Limit Card
B = No Limit function, field access to contactor coil
- V. Power supply voltage
H = High voltage universal 100 to 240 Vac/dc, 50/60 Hz
L = Low voltage universal 24 to 28 Vac/dc, 50/60 HZ
1 = 24 Vac (contactor voltage), 50/60 Hz
2 = 120 Vac (contactor voltage), 50/60 Hz
3 = 208/240 Vac (contactor voltage), 50/60 Hz
- VI. Customization
Any four letters or numbers for communications, firmware and other non-critical cosmetic options.

ENGINEERING CONSIDERATIONS (NOT FOR FIELD REPRESENTATIVE'S USE):

Use - For use only in products where the acceptability of the combination is determined by Underwriters Laboratories Inc.

Conditions of Acceptability - When installed in the final use equipment, etc., the following are among the considerations to be made:

1. These devices are to be used within their Recognized ratings as specified above.
2. For units provided without integrated heatsink, evaluation of end product temperature in the final assembly will be required.
3. The devices must be mounted in an end use enclosure.
4. Temperature of plastic enclosure not to exceed 130 °C
5. Temperature of Solid state relay junction not to exceed 125 °C.
6. Use of thermal compound/pad between SSR and heat sink required.

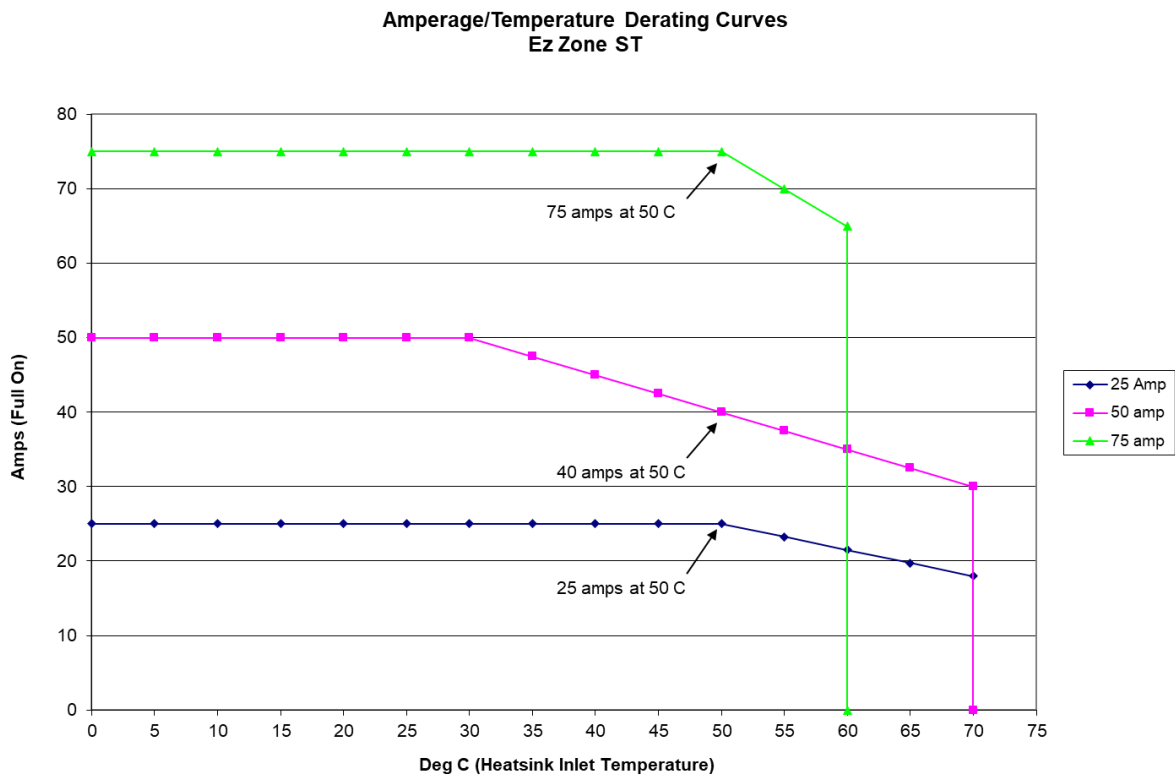


FIGURE 1